RF Transformer

TC2-1TG2+

 50Ω

3 to 300 MHz

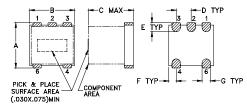
Maximum Ratings

Operating Temperature	-20°C to 85°C
Storage Temperature	-55°C to 100°C
RF Power	0.25W
DC Current	30mA
B	60 P. N. 1. 1

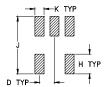
Pin Connections

PRIMARY DOT	6
PRIMARY	4
SECONDARY DOT	1
SECONDARY	3
SECONDARY CT	2

Outline Drawing AT224-3



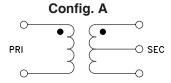
PCB Land Pattern



Suggested Layout, Tolerance to be within ±002

Outline Dimensions (inch)

Α	В	С	D	E	F
.150	.150	.150	.050	.030	.025
3.81	3.81	3.81	1.27	0.76	0.64
G	Н	J	K		wt
.028	.065	.190	.030		grams
0.71	1.65	4.83	0.76		0.10



Features

- suitable for tin/lead and RoHS solder systems
- good return loss
- excellent amplitude unbalance, (0.5 dB typ.) and phase unbalance, (4 deg. typ.) in 1 dB bandwidth
- aqueous washable

Applications

- impedance matching
- balanced to unbalanced transformation
- push-pull amplifiers

CASE STYLE: AT224-3

+RoHS Compliant

The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications



Electrical Specifications

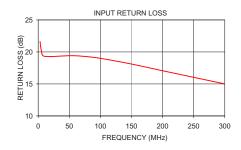
			_					
Ω RATIO (Secondary/Primary)	FREQUENCY (MHz)	INS	INSERTION LOSS*		UNBAI (De	ASE LANCE eg.) /p.	AMPLITUDE UNBALANCE (dB) Typ.	
		3 dB	2 dB	1 dB	1 dB	2 dB	1 dB	2 dB
		MHz	MHz	MHz	bandwidth	bandwidth	bandwidth	bandwidth
2	3-300	_	_	3-300	4	_	0.5	_

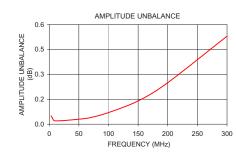
^{*} Insertion Loss is referenced to mid-band loss, .4 dB typ.

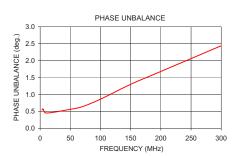
Typical Performance Data

FREQUENCY (MHz)	INSERTION LOSS (dB)	INPUT R. LOSS (dB)	AMPLITUDE UNBALANCE (dB)	PHASE UNBALANCE (Deg.)
3.00	0.38	21.63	0.05	0.54
5.00	0.33	20.24	0.04	0.57
10.00	0.34	19.32	0.02	0.45
50.00	0.37	19.41	0.03	0.56
70.00	0.40	19.34	0.04	0.64
100.00	0.44	19.00	0.07	0.86
150.00	0.52	18.11	0.14	1.30
200.00	0.60	17.06	0.25	1.68
300.00	0.80	15.00	0.53	2.44









- A. Performance and quality attributes and conditions not expressly stated in this specification document are intended to be excluded and do not form a part of this specification document.

 B. Electrical specifications and performance data contained in this specification document are based on Mini-Circuit's applicable established test performance criteria and measurement instructions.

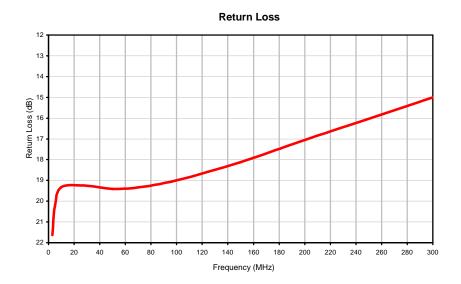
 C. The parts covered by this specification document are subject to Mini-Circuits standard limited warranty and terms and conditions (collectively, "Standard Terms"); Purchasers of this part are entitled to the rights and benefits contained therein. For a full statement of the Standard Terms and the exclusive rights and remedies thereunder, please visit Mini-Circuits' website at www.ninicircuits.com/MCLStore/terms.jsp

Typical Performance Data

FREQUENCY (MHz)	INSERTION LOSS (dB)	RETURN LOSS (dB)
3.00	0.38	21.63
5.00	0.33	20.24
10.00	0.34	19.32
30.00	0.34	19.26
50.00	0.37	19.41
70.00	0.40	19.34
100.00	0.44	19.00
150.00	0.52	18.11
200.00	0.60	17.06
300.00	0.80	15.00

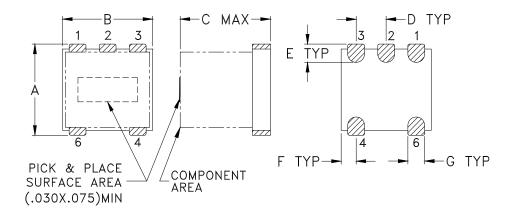
Typical Performance Curves



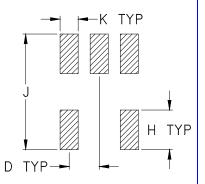


AT224-3

Outline Dimensions



PCB Land Pattern



Suggested Layout, Tolerance to be within ±.002

CASE#	A	В	C	D	Е	F	G	Н	J	K	L	WT. GRAMS
AT224-3	.150	.150	.150	.050	.030	.025	.028	.065	.190	.030		.10
A1224-3	(3.81)	(3.81)	(3.81)	(1.27)	(0.76)	(0.64)	(0.71)	(1.65)	(4.83)	(0.76)		.10

Dimensions are in inches (mm). Tolerances: 2 Pl. ± .01; 3 Pl. ± .005

Notes:

- 1. Open style, ceramic base.
- 2. Termination finish: 3.15-5.12 μ inch (.08-.130 microns) Gold over 78–236 μ inch (1.98-6.0 microns) Nickel plate.



INTERNET http://www.minicircuits.com

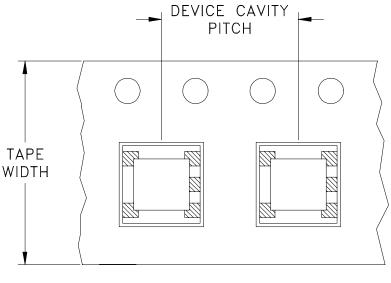
P.O. Box 350166, Brooklyn, New York 11235-0003 (718) 934-4500 Fax (718) 332-4661

Distribution Centers NORTH AMERICA 800-654-7949 • 417-335-5935 • Fax 417-335-5945 • EUROPE 44-1252-832600 • Fax 44-1252-837010

Mini-Circuits ISO 9001 & ISO 14001 Certified

Tape & Reel Packaging TR-F17

DEVICE ORIENTATION IN T&R



DIRECTION OF FEED

Tape Width, mm	Device Cavity Pitch, mm	Reel Size, inches	Devices	s per Reel
			Small	20
			quantity	50
		7	standards	100
12	8		(see note)	200
				500
		12	Standard	1000
		13		2000

Note: Please Consult individual model data sheet to determine device per reel availability.

Mini-Circuits carrier tape materials provide protection from ESD (Electro-Static Discharge) during handling and transportation. Tapes are static dissipative and comply with industry standards EIA-481/EIA-541.

Go to: www.minicircuits.com/pages/pdfs/tape.pdf

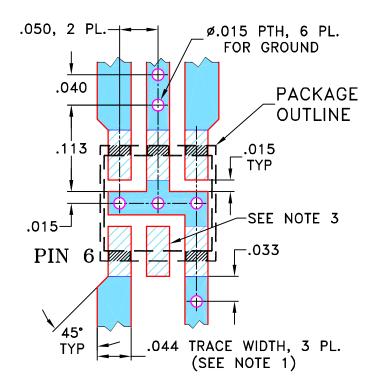


Mini-Circuits ISO 9001 & ISO 14001 Certified

THIRD ANGLE PROJECTION	
Ψ	

		REVISIONS			
REV	ECN No.	DESCRIPTION	DATE	DR	AUTH
OR	M106563	NEW RELEASE	08/23/06	AV	IG

SUGGESTED MOUNTING CONFIGURATION FOR AT224/DB714 CASE STYLE, "gs/ha/hd" PIN CONNECTIONS (FOR SINGLE ENDED TO BALANCED APPLICATION)



- NOTES: 1. TRACE WIDTH IS SHOWN FOR ROGERS RO4350B WITH DIELECTRIC THICKNESS .020" ± .0015"; COPPER: 1/2 OZ. ON EACH SIDE. FOR OTHER MATERIALS TRACE WIDTH MAY NEED TO BE MODIFIED.
 - 2. BOTTOM SIDE OF THE PCB IS CONTINUOUS GROUND PLANE.
 - 3. THIS PAD IS NOT REQUIRED FOR AT224 CASE STYLE.

DENOTES PCB COPPER LAYOUT WITH SMOBC (SOLDER MASK OVER BARE COPPER)

DENOTES COPPER LAND PATTERN FREE OF SOLDER MASK

				_						
UNLESS OTHERWISE SPECIFIED)	INITIALS	DATE					• 4 ®		
DIMENSIONS ARE IN INCHES	DRAWN	AV	07/28/06		\perp Mini	ı — C	ircu	1ts :	Neptu	ne Avenue NY 11235
TOLERANCES ON:	CHECKED	IL	08/23/06		T			Bro	okiyn	NI IIZJO
3 PL DECIMALS ± .005	APPROVED	IG	08/23/06							
FRACTIONS ±				PL, gs/ha/hd, AT224/DB714, TC/TCM, TB					TB-145	
Mini	Mini-Circuits ®]	6 / /	•	,	, ,	•	
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	ASHEETA1.	DWG REV:A DA	TE:01/12/95	5	70F L&44		0.1		T	Or I



Environmental Specifications

ENV02

All Mini-Circuits products are manufactured under exacting quality assurance and control standards, and are capable of meeting published specifications after being subjected to any or all of the following physical and environmental test.

Specification	Test/Inspection Condition	Reference/Spec
Operating Temperature	-20° to 85°C Ambient Environment	Individual Model Data Sheet
Storage Temperature	-55° to 100° C Ambient Environment	Individual Model Data Sheet
Humidity	90 to 95% RH, 240 hours, 50°C	MIL-STD-202, Method 103, Condition A, Except 50°C and end-point electrical test done within 12 hours
Thermal Shock	-55° to 100°C, 100 cycles	MIL-STD-202, Method 107, Condition A-3, except +100°C
Solder Reflow Heat	Sn-Pb Eutetic Process: 225°C peak Pb-Free Process 245° - 250°C peak	J-STD-020, Table 4-1, 4-2 and 5-2, Figure 5-1
Solderability	10X Magnification	J-STD-002, 95% Coverage
Vibration (High Frequency)	20g peak, 10-2000 Hz, 12 times in each of three perpendicular directions (total 36)	MIL-STD-202, Method 204, Condition D
Mechanical Shock	50g, 11 ms, 1/2-sine, 18 shocks: 3 each direction, each of 3 axes	MIL-STD-202, Method 213, Condition A
Marking Resistance to Solvents	Isopropyl alcohol + mineral spirits at 25°C; terpene defluxer at 25°C; distilled water + proylene glycol monomethyl ether + monoethanolamine at 63°C to 70°C	MIL-STD-202, Method 215

ENV02 Rev: A

02/25/11

M130240 File: ENV02.pdf

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